



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL21C7R5CBANNNC
- Description : CAP, 7.5pF, 50V, ±0.25pF, C0G, 0805

A. Samsung Part Number

			<u>CL</u>	<u>21</u>	<u>C</u>	<u>7R5</u>	<u>C</u>	B	<u>A</u>	<u>N</u>	N	N	<u>C</u>			
			1	2	3	4	5	6	1	8	9	10	1			
1	Series	Samsung Multi-layer Ceramic Capacitor														
2	Size	0805	(inch co	ode)		L:	2.0	± 0.1		mm		W:	1.25	± 0.1	mm	
							0		_		_					
3	Dielectric	C0G					(8)	Inne	r ele	ctroc	le		Ni			
4	Capacitance	7.5	рF					Term	ninat	tion			Cu			
5	Capacitance	±0.25	рF					Plati	ng				Sn 10	0%	(Pb Free)	
	tolerance						9	Prod	uct				Norma	al		
6	Rated Voltage	50	V				10	Spec	ial				Reser	ved for	future use	
$\bigcirc$	Thickness	0.65	± 0.1	mm			1	Pack	agir	ng			Cardb	oard T	ype, 7" reel	

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1M±10% 0.5~5Vrms						
Q	550 min							
Insulation	10,000Mohm or 500Mohm ⋅ μF	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance No abnormal exterior appearance		Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	C0G							
Characterisitcs	(From -55 $^\circ$ C to 125 $^\circ$ C, Capacitance change shoud be within ±30PPM/ $^\circ$ C)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or $\pm 0.5$ pF whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger							
	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours $\times$ 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 125 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature					
	Q : 275 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm $\cdot \mu F$						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	Min. operating temperatur $\rightarrow$ 25 °C					
	Tan δ, IR : initial spec.	$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C					
		5 cycle test					

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.